

# Product Portfolio and Features

● Essential features contained | ○ Optional features

Product Package & Mesh Technology				
	Professional Basic	eDesign	Professional	Advanced
<b>True 3D Mesh</b>				
eDesign	●	●	●	●
Boundary Layer Mesh (BLM), Tetra	●		●	●
Solid (Hexa, Prism, Pyramid, Hybrid)				●
<b>2.5D Mesh</b>				
Shell				●

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Standard Injection Molding				
	Professional Basic	eDesign	Professional	Advanced
<b>Solver Capabilities</b>				
Simultaneous Filling Analysis (max.)	1	1	1	3
Parallel Processing (PP)	4	4	8	12
Thermoplastic Injection Molding	●	●	●	●
Reaction Injection Molding (RIM)	●	●	●	●
Cloud Extension	●	●	●	●
<b>Simulation Capabilities</b>				
Filling	●	●	●	●
Surface Defect Prediction	●	●	●	●
Venting Analysis	●	●	●	●
Gate Location	●	●	●	●
Cold & Hot Runners	●	●	●	●
Runner Balancing	●	●	●	●
Packing		●	●	●
Cooling		●	●	●
Transient Mold Cooling or Heating		●	●	●
Conformal Cooling		●	●	●
3D Coolant CFD		○	●	●
Rapid Temperature Cycling		●	●	●
Induction Heating		●	●	●
Heating Elements		●	●	●
Warpage		●	●	●
Insert Molding	●	●	●	●
Multi-shot Sequential Molding		●	●	●

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Solution Add-on				
	Professional Basic	eDesign	Professional	Advanced
<b>CAD Interoperability</b>				
SYNC	○	○	○	○
Moldex3D CADdoctor	○	○	○	○
Moldex3D Cooling Channel Designer (CCD)		○	○	○
<b>Fiber Reinforced Plastics</b>				
Fiber	○	○	○	○
Stress		○	○	○
FEA Interface	○	○	○	○
Micromechanics Interface	○	○	○	○
Moldex3D Digimat-RP	○	○	○	○
<b>DOE</b>				
Expert		○	○	○
<b>Thermal Management</b>				
Advanced Hot Runner		○	○	○
In-Mold Decoration(IMD)			○	○
<b>Optical</b>				
Optics				○
Viscoelasticity (VE)		○	○	○
<b>Special Molding Processes</b>				
Powder Injection Molding (PIM)	○	○	○	○
Foam Injection Molding		○	○	○
Gas-Assisted Injection Molding (GAIM)			○	○
Water-Assisted Injection Molding (WAIM)			○	○
Co-Injection			○	○
Bi-Injection			○	○
PU Chemical Foaming			○	○
Compression Molding (CM)				○
Injection Compression Molding (ICM)				○
Resin Transfer Molding (RTM)				○

1. Moldex3D SYNC supports PTC® Creo®, NX, and SOLIDWORKS®.

2. Moldex3D FEA Interface supports Abaqus, ANSYS, MSC.Nastran, Nastran, NX Nastran, LS-DYNA, MSC.Marc, and Radioss.

3. Moldex3D Micromechanics Interface supports Digimat and CONVERSE.

4. Database: Thermoplastics materials, thermoset materials, molding materials, coolant materials, and mold materials.

System Requirements	
<b>Platform</b>	
Windows	Windows 10, 8, 7, Server 2012, 2008 R2, HPC Server 2008 R2
<b>Hardware</b>	
Minimum	Intel® Core i7 processor, 16 GB RAM, and at least 1 TB free space
Recommended	Intel® Xeon® E5 processor, 32 GB RAM, and at least 2 TB free space